

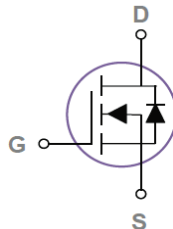
N-Channel Enhancement Mode MOSFET

Features

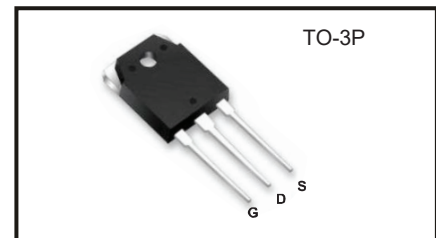
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Applications

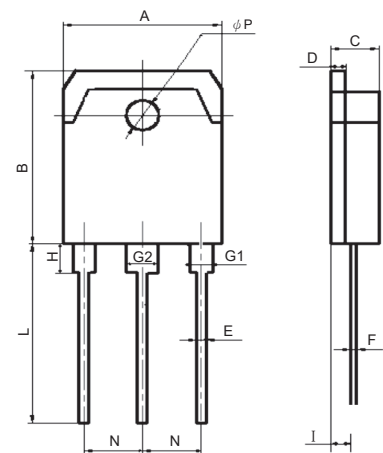
- DC-DC Converters
- DC-AC Inverters for UPS
- SMPS and Motor Controls



V_{DSS}	200V
$I_{D(@25^{\circ}C)}$	50A
$R_{DS(ON)}$ typ.	30m Ω



Package Dimensions



Absolute Maximum Ratings

(T_c = 25°C unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage (Note1)	V_{DSS}	200	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current Continuous	I_D	50	A
Pulsed Drain Current (Note2)	I_{DM}	200	A
Single Pulse Avalanche Energy (Note2)	E_{AS}	1514	mJ
Avalanche Energy ,Repetitive (Note1)	E_{AR}	6.05	mJ
Avalanche Current (Note1)	I_{AS}	17.4	A
Power Dissipation @ T _c = 25°C	P_D	250	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction to Case	$R_{\theta JC}$	0.5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

SYMBOLS	MILLIMETERS	
	MIN	MAX
A	15.10	15.90
B	19.50	20.50
C	4.70	4.90
D	1.40	1.60
E	0.90	1.10
F	0.50	0.70
G1	2.00	2.20
G2	3.00	3.20
H	3.00	3.60
I	1.20	1.60
L	19.50	20.90
N	5.25	5.65
ΦP	3.10	3.30

Electrical Characteristics @ T_c =25°C (unless otherwise specified)

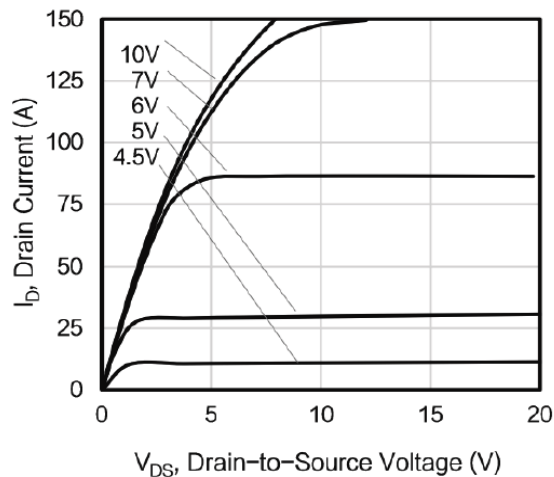
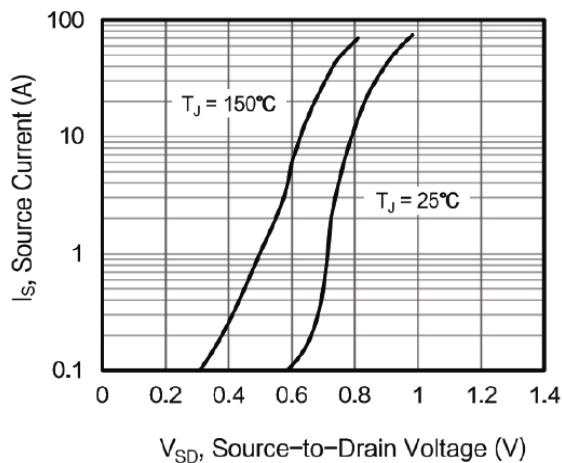
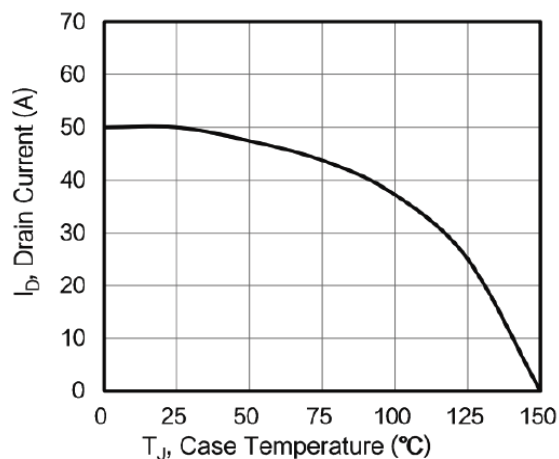
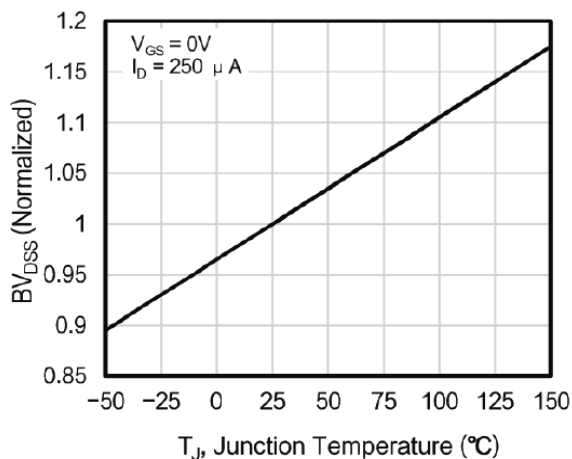
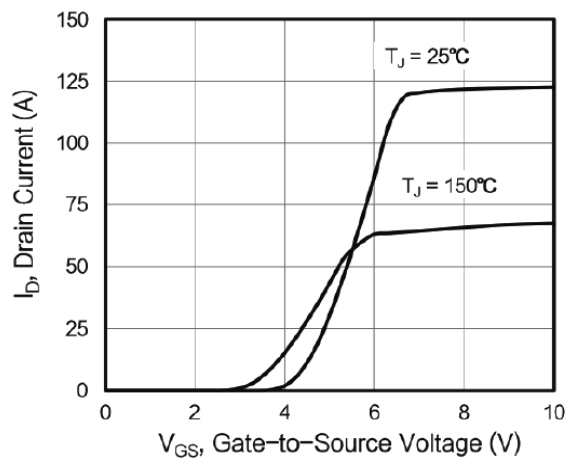
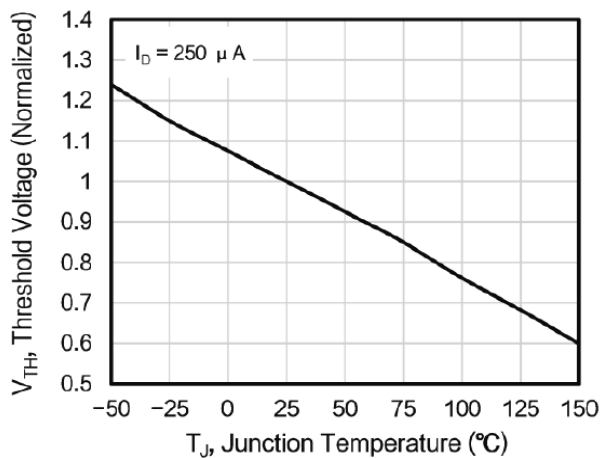
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
OFF Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V , I _{DS} = 0.25mA	200	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0V , V _{DS} = 200V	-	-	1	μ A
Gate To Source Forward Leakage	I _{GSS}	V _{GS} = ±20V , V _{DS} = 0V	-	-	±100	nA
ON Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 0.25mA	2.0	-	4.0	V
Drain-Source On-State Resistance (Note4)	R _{DS(on)}	V _{GS} = 10V , I _D = 25A	-	30	38	mΩ
Dynamic Characteristics Note2						
Input Capacitance	C _{iss}	V _{DS} = 25V	-	3538	-	pF
Output Capacitance	C _{oss}	V _{GS} = 0V	-	657	-	
Reverse Transfer Capacitance	C _{rss}	Freq. = 1.0MHz	-	280	-	
Switching Characteristics Note2						
Turn-On Delay Time	t _{d(on)}	V _{DS} = 100V	-	58	-	ns
Rise Time	t _r	V _{GS} = 10V	-	195	-	
Turn-Off Delay Time	t _{d(off)}	I _D = 50A	-	841	-	
Fall Time	t _f	R _G = 25Ω	-	326	-	
Total Gate Charge	Q _g	V _{DS} = 160V	-	200	-	nC
Gate to Source Charge	Q _{gs}	V _{GS} = 0 to 10V	-	16	-	
Gate to Drain Charge	Q _{gd}	I _D = 50A	-	65	-	
Source-Drain Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V , I _S = 25A	-	-	1.5	V
Continuous Source Current	I _{SD}	Integral PN-diode in MOSFET	-	-	50	A
Pulsed Source Current	I _{SM}		-	-	200	
Reverse Recovery Time	T _{rr}	I _S = 50A • V _{GS} = 0V	-	236	-	ns
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/ μ s	-	3.37	-	μ C

Notes:

1.Repetitive raating : Pulse width limited by maximum junction temperature

2.L=10mH, V_{DD}=50V, R_G=25Ω, Starting T_J=25°C

3.Pulse test : Pulse width ≤ 300 μs, duty cycle ≤ 1%

Typical Performance Characteristics , $T_J = 25^\circ\text{C}$ unless otherwise noted
Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

Figure 2. Body Diode Forward Voltage

Figure 3. Drain Current vs. Temperature

Figure 4. BV_{DSS} Variation vs. Temperature

Figure 5. Transfer Characteristics

Figure 6. Threshold Voltage vs. Temperature


Typical Performance Characteristics , $T_J = 25^\circ\text{C}$ unless otherwise noted

Figure 7. Capacitance

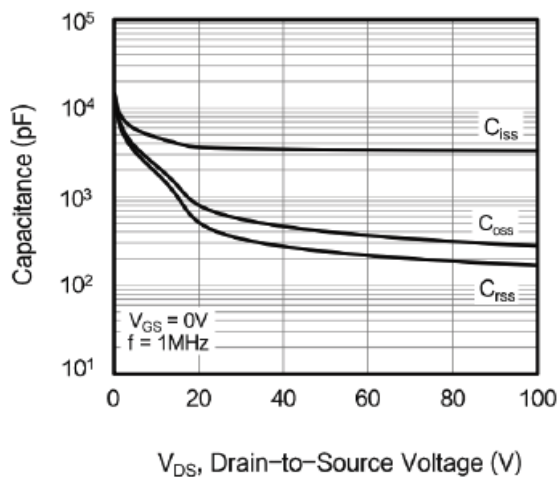


Figure 8. Gate Charge

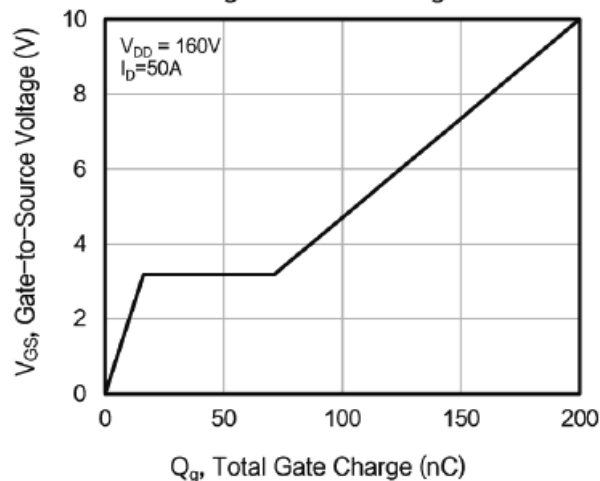


Figure 9. Transient Thermal Impedance

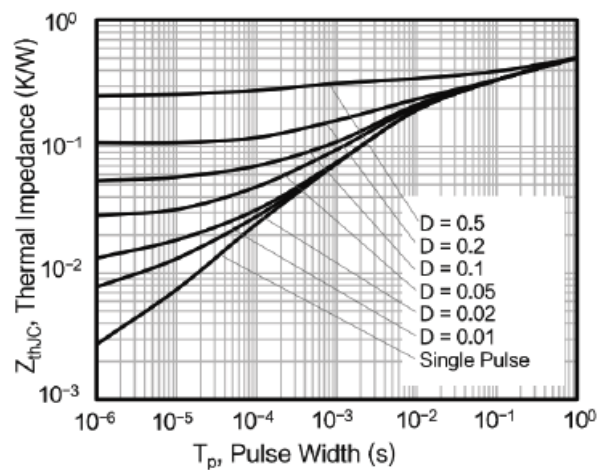


Figure 10. Safe Operating Area

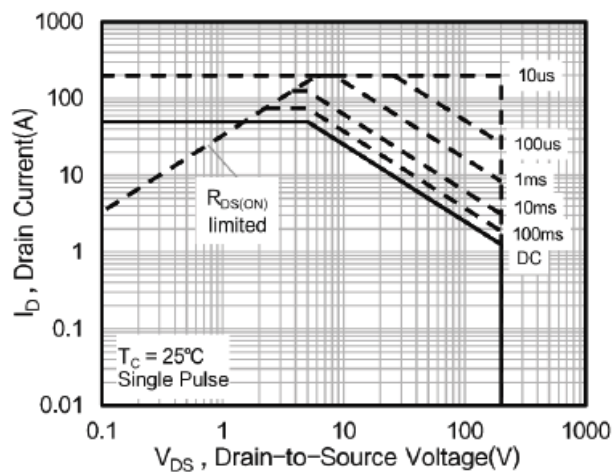
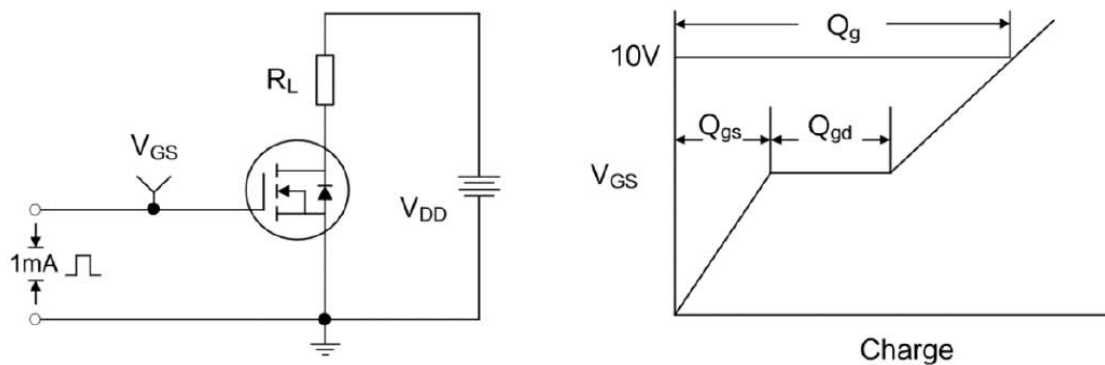
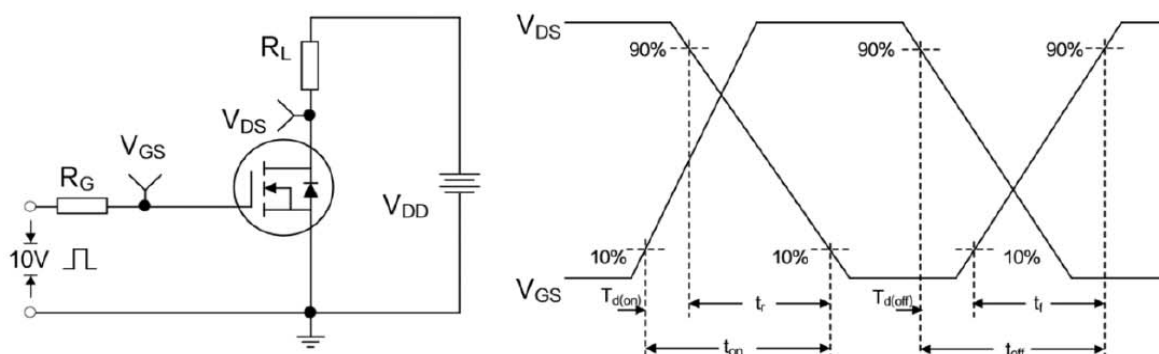
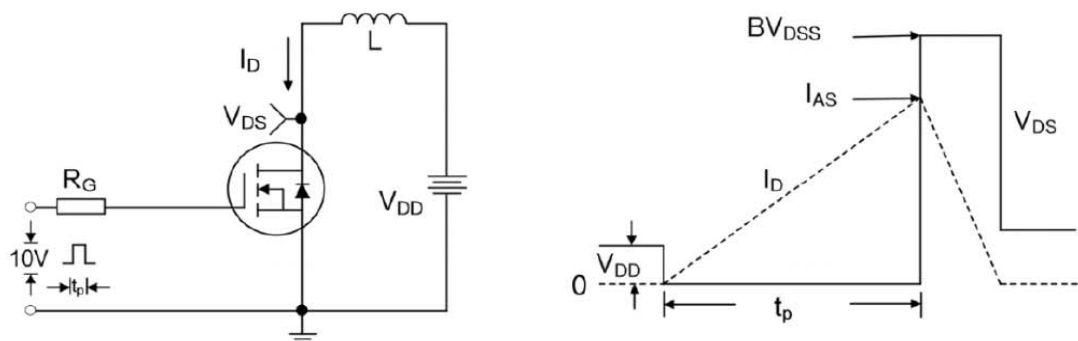


Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


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